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(12) **United States Design Patent**
Zimmer

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(54) **HOUSING FOR ELECTRONIC MODULES WITH COOLING FINS**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/179**
(58) **Field of Classification Search**
CPC F28D 1/0246; F28D 1/0426; F28D 15/02; F28D 15/0266; F28D 15/0275; F28D 15/04; F28F 13/003; F28F 13/12; F28F 1/325; F04D 25/0613; F04D 25/068; F04D 29/281422; F21V 29/2293; F21V 29/2231; G03B 21/16; G06F 1/20; G06F 1/203; H01L 23/34; H01L 23/367; H01L 23/3672; H01L 23/40; H01L 23/4006; H01L 23/4093; H01L 23/427; H01L 23/467; H05K 7/20; H05K 7/20127; H05K 7/20145; H05K 7/20154; H05K 7/20172; H05K 7/20336
USPC D13/179; 165/80.3, 104.26, 104.33, 165/122, 151, 185; 257/706, 707, 718–722; 361/695, 697, 700, 702, 704, 709, 710, 361/711, 719
See application file for complete search history.

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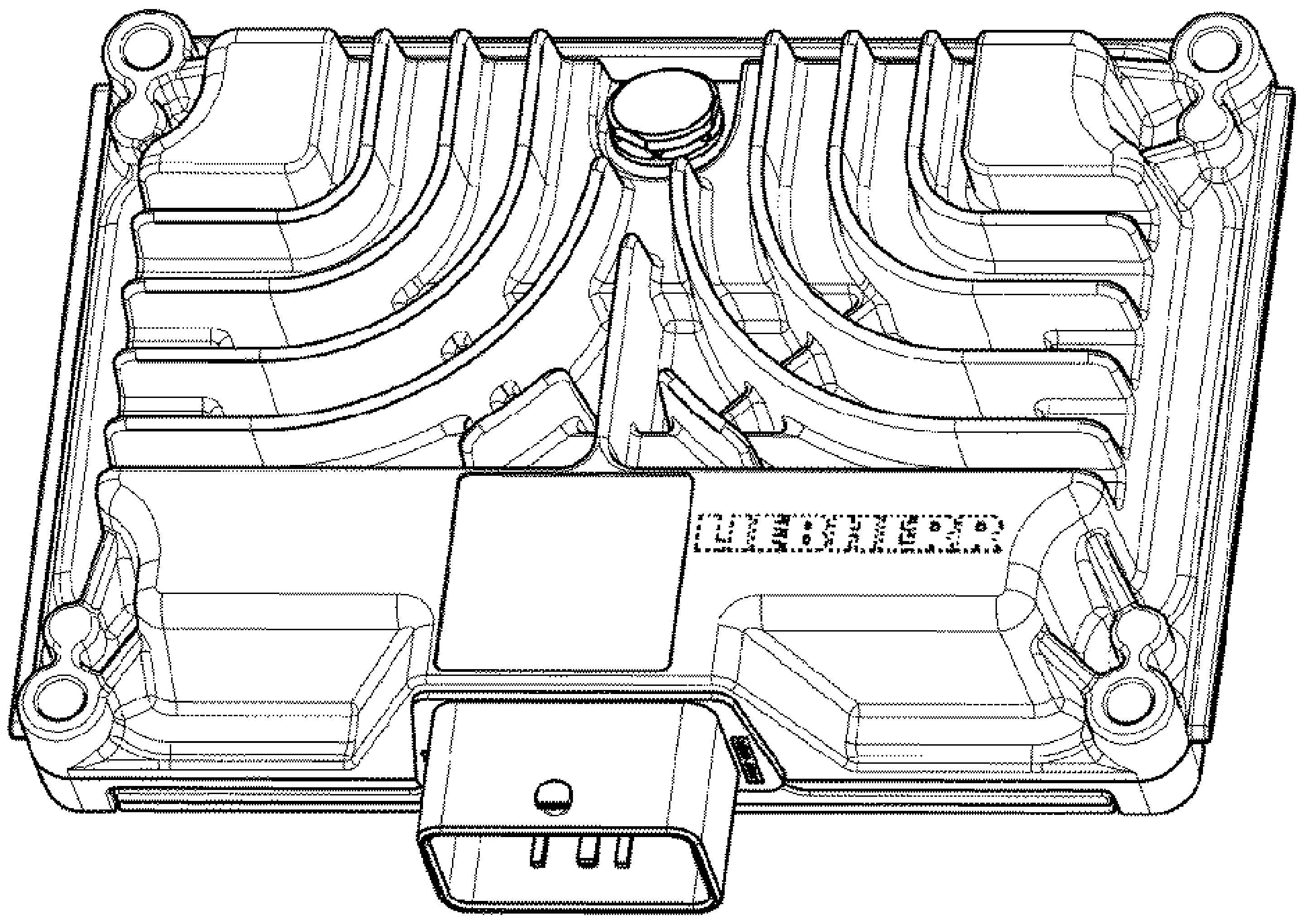
(57) **CLAIM**

The ornamental design for a housing for electronic modules with cooling fins, as shown and described.

DESCRIPTION

FIG. **1** is a front view of a design for a housing for electronic modules with cooling fins according to the present disclosure.
FIG. **2** is a back view of the housing for electronic modules with cooling fins of FIG. **1**.
FIG. **3** is a left view of the housing for electronic modules with cooling fins of FIG. **1**.
FIG. **4** is a right view of the housing for electronic modules with cooling fins of FIG. **1**.
FIG. **5** is a top view of the housing for electronic modules with cooling fins of FIG. **1**.
FIG. **6** is a bottom view of the housing for electronic modules with cooling fins of FIG. **1**; and,
FIG. **7** is a perspective view of the housing for electronic modules with cooling fins of FIG. **1**.
The solid lines in FIGS. **1-7** illustrate a housing for electronic modules with cooling fins according to the present disclosure. The broken lines form no part of the claimed design.

1 Claim, 7 Drawing Sheets



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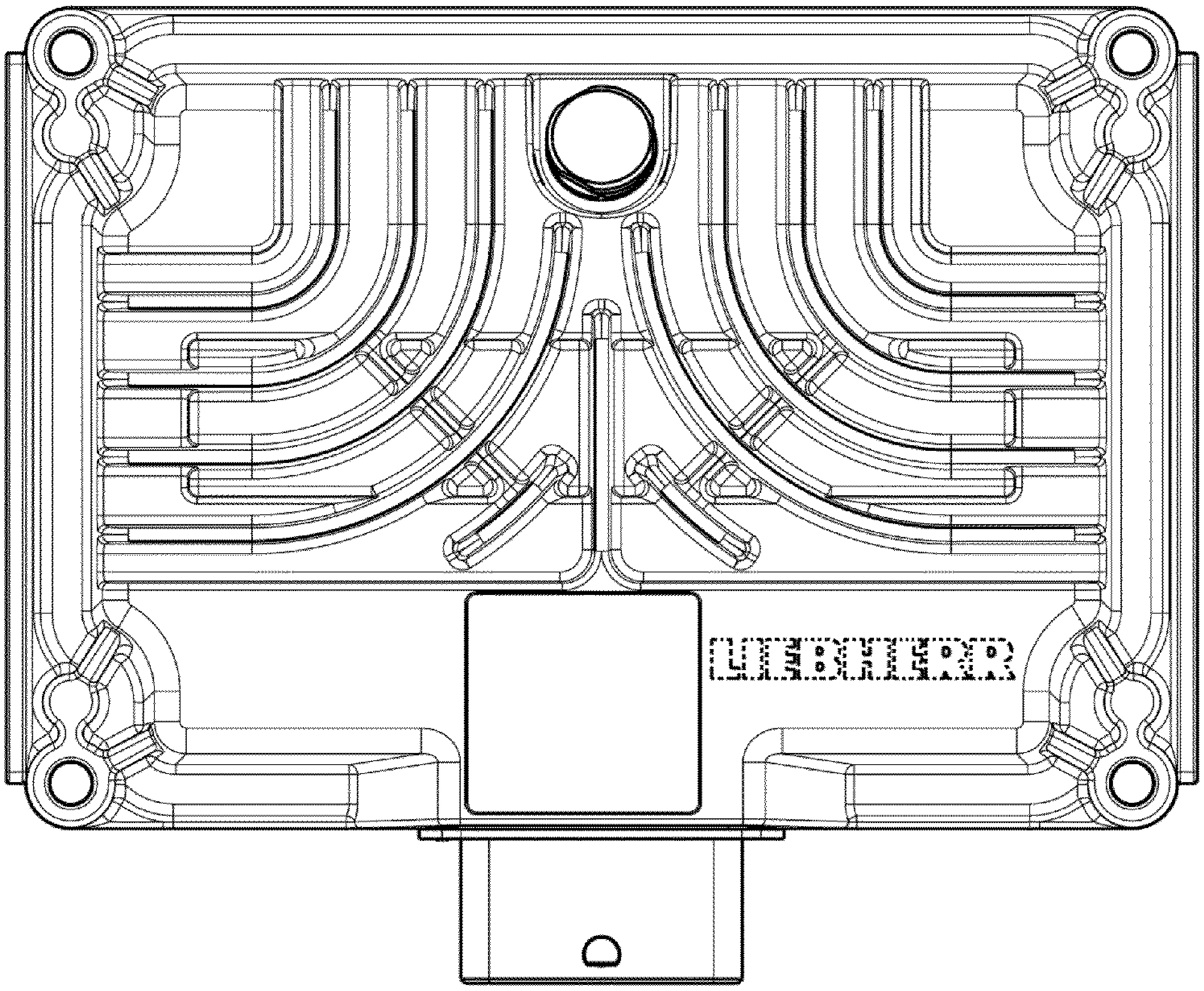

FIG. 1

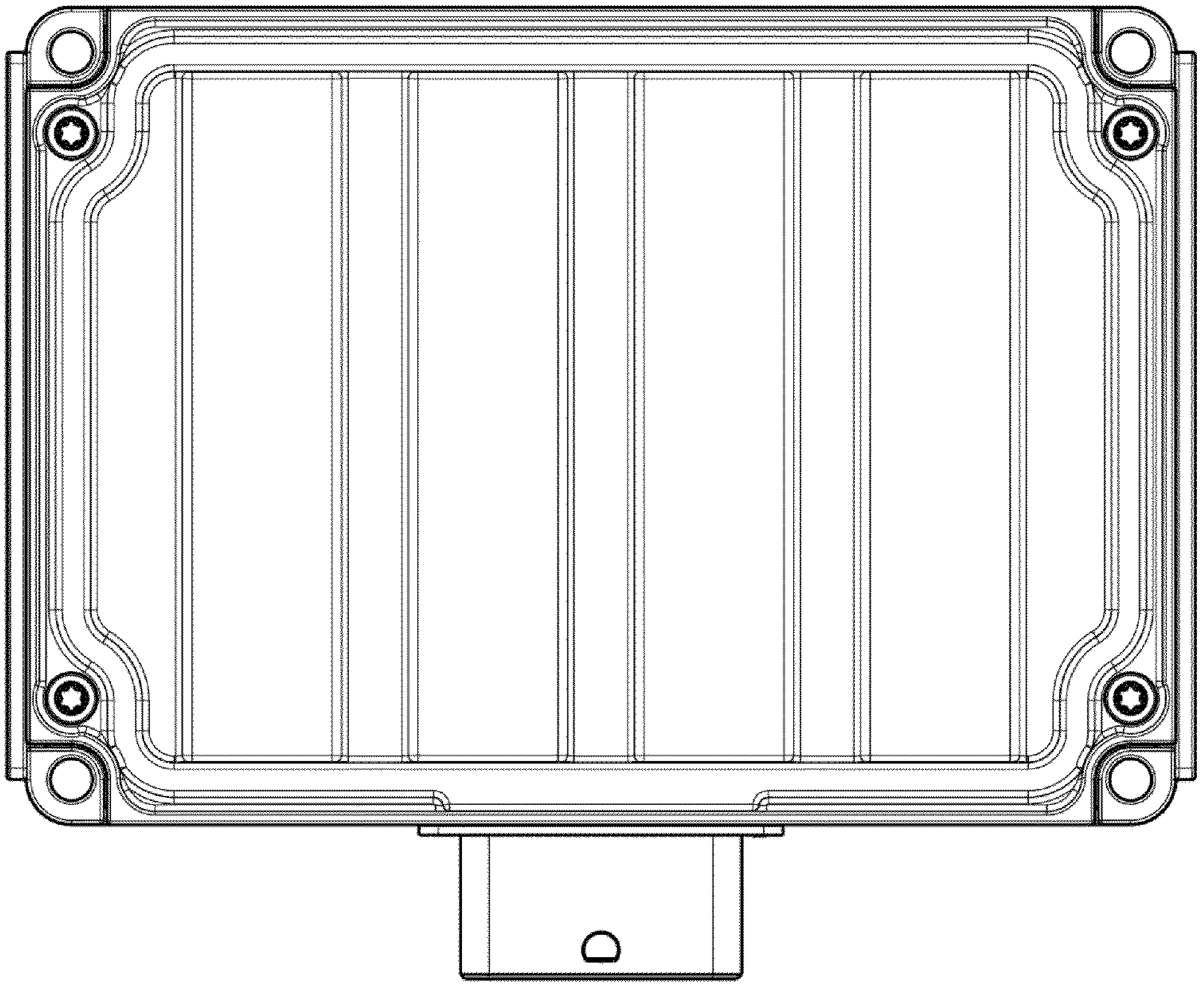

FIG. 2

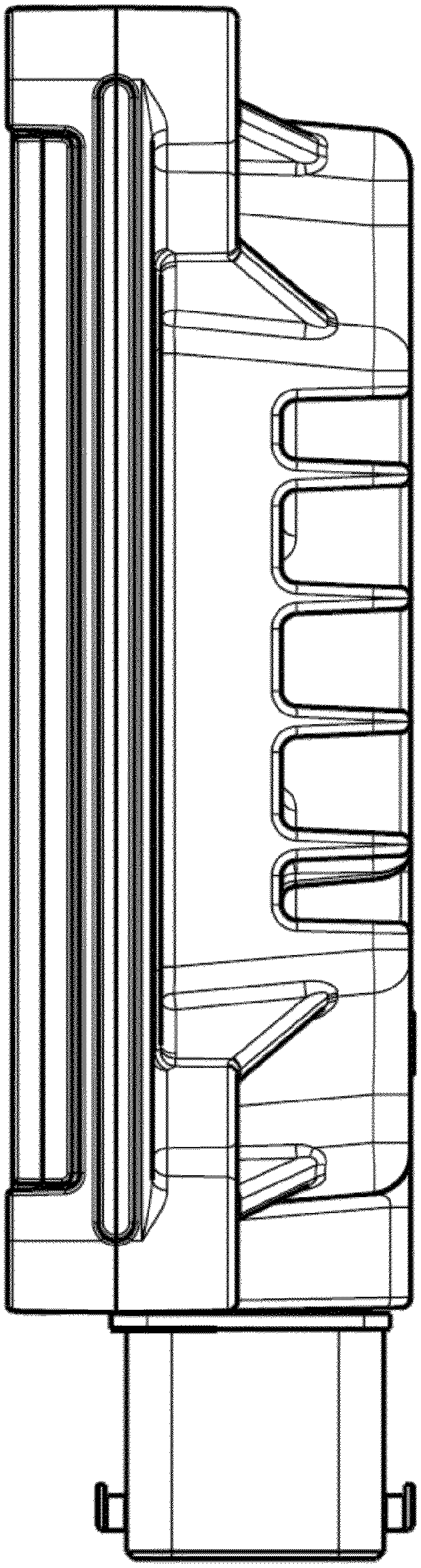

FIG. 3

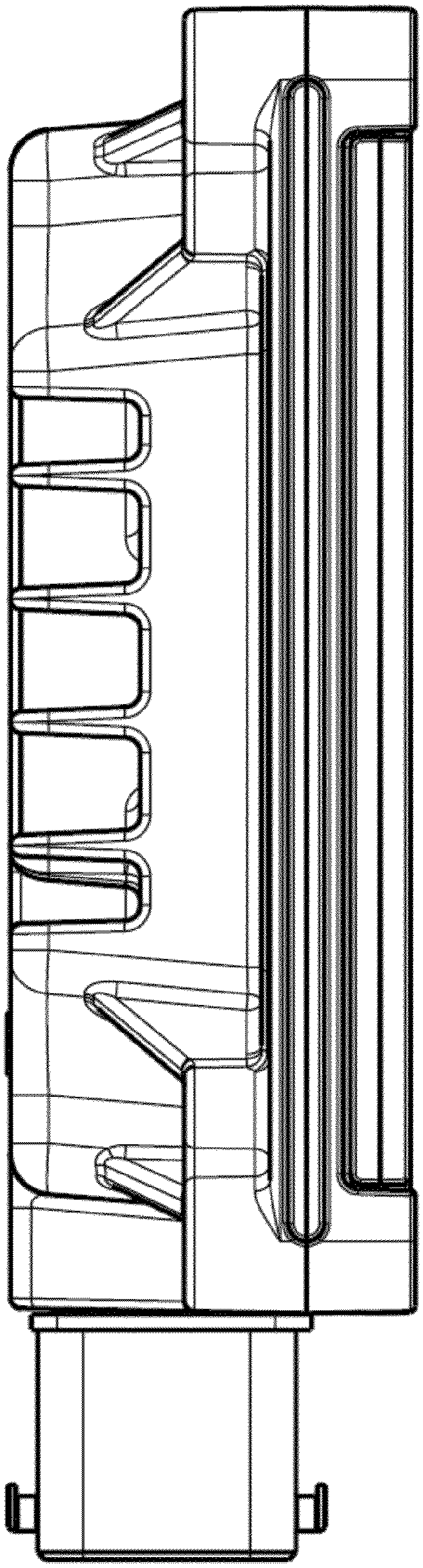

FIG. 4

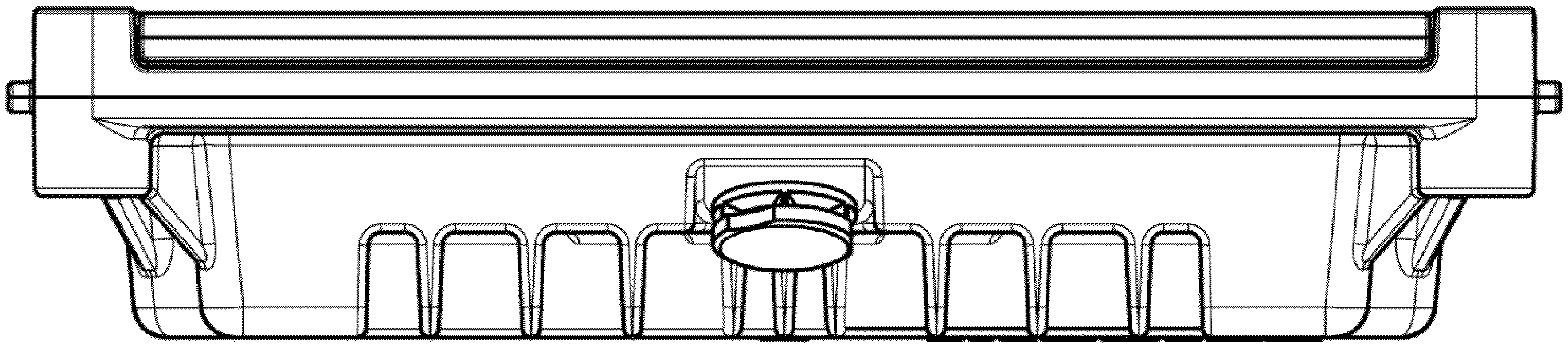

FIG. 5

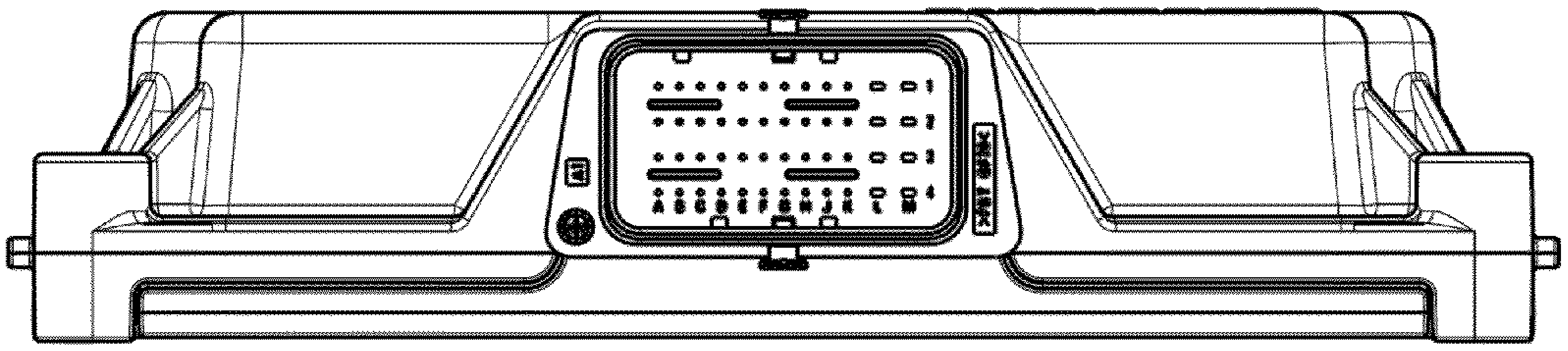

FIG. 6

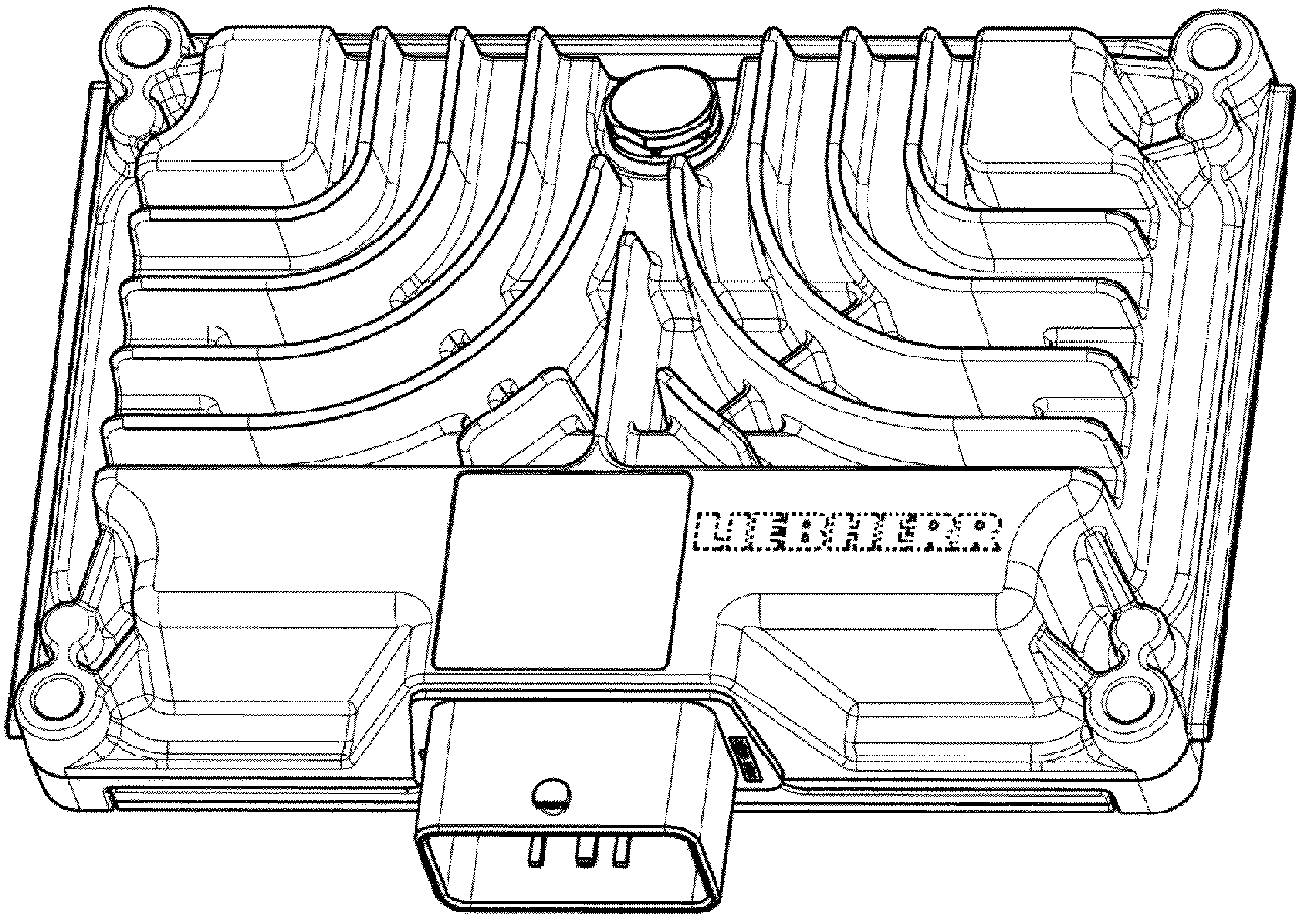

FIG. 7